

Title (en)  
SINTERED SLIDING MEMBER

Title (de)  
GESINTERTES GLEITELEMENT

Title (fr)  
ÉLÉMENT COULISSANT FRITTÉ

Publication  
**EP 2511388 A4 20170503 (EN)**

Application  
**EP 10835953 A 20101207**

Priority  
• JP 2009278052 A 20091207  
• JP 2010071879 W 20101207

Abstract (en)  
[origin: WO2011071033A1] Provided is a novel sintered sliding member having excellent heat resistance, corrosion resistance, and abrasion resistance. The sintered sliding member includes, by mass%, 7.7% to 30.3% of Cu, 2.0% to 20.0% of Sn, and 0.3% to 7.0% of boron nitride, with the balance comprising Ni and inevitable impurities. The sintered sliding member optionally includes 0.1% to 3.0% of C or 0.1% to 0.7% of P. Porosity is 5% to 25%.

IPC 8 full level  
**C22C 19/03** (2006.01); **C22C 1/04** (2006.01); **C22C 1/08** (2006.01); **C22C 19/00** (2006.01); **C22C 30/02** (2006.01); **C22C 32/00** (2006.01); **F16C 33/12** (2006.01)

CPC (source: EP US)  
**C22C 1/0433** (2013.01 - EP US); **C22C 1/08** (2013.01 - EP US); **C22C 19/002** (2013.01 - EP US); **C22C 19/03** (2013.01 - EP US); **C22C 30/02** (2013.01 - EP US); **C22C 32/0068** (2013.01 - EP US); **F16C 33/121** (2013.01 - EP US); **F16C 2204/52** (2013.01 - EP US); **F16C 2220/20** (2013.01 - EP US); **F16C 2300/54** (2013.01 - EP US); **F16C 2360/22** (2013.01 - EP US)

Citation (search report)  
• [A] US 2004071374 A1 20040415 - TOMITA HIROTSUGU [JP], et al  
• [A] JP 2004148469 A 20040527 - MITSUI KENSAKU TOISHI KK  
• [A] JP 2006097797 A 20060413 - OILES INDUSTRY CO LTD  
• [A] JP H09285888 A 19971104 - NHK SPRING CO LTD  
• See references of WO 2011071033A1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**WO 2011071033 A1 20110616**; BR 112012013137 A2 20170321; BR 112012013137 B1 20180206; CN 102648299 A 20120822; CN 102648299 B 20131106; EP 2511388 A1 20121017; EP 2511388 A4 20170503; EP 2511388 B1 20180314; JP 5337884 B2 20131106; JP WO2011071033 A1 20130422; US 2012204677 A1 20120816; US 8709124 B2 20140429

DOCDB simple family (application)  
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